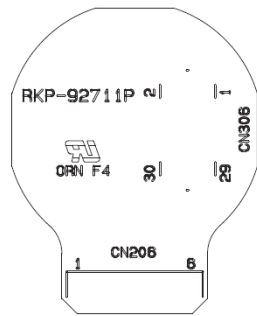
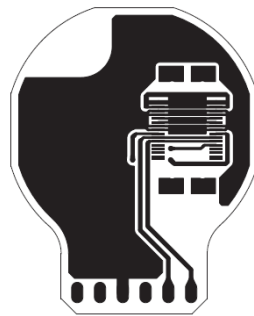


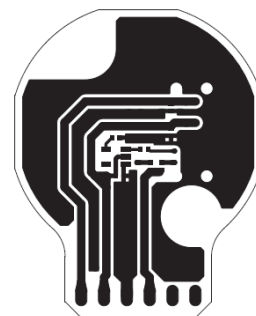
SILK PRINT FOR PARTS SIDE



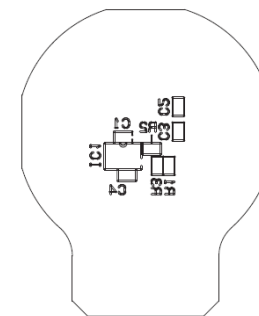
PARTS SIDE



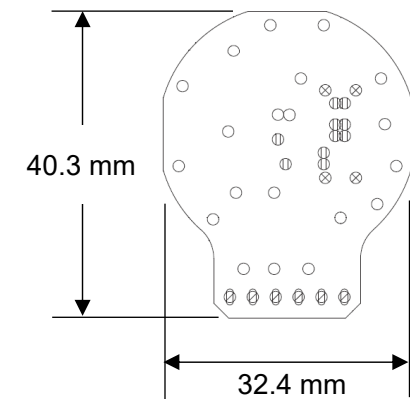
SOLDERING SIDE



SILK PRINT FOR SOLDERING SIDE



THROUGH HOLE FOR PARTS SIDE

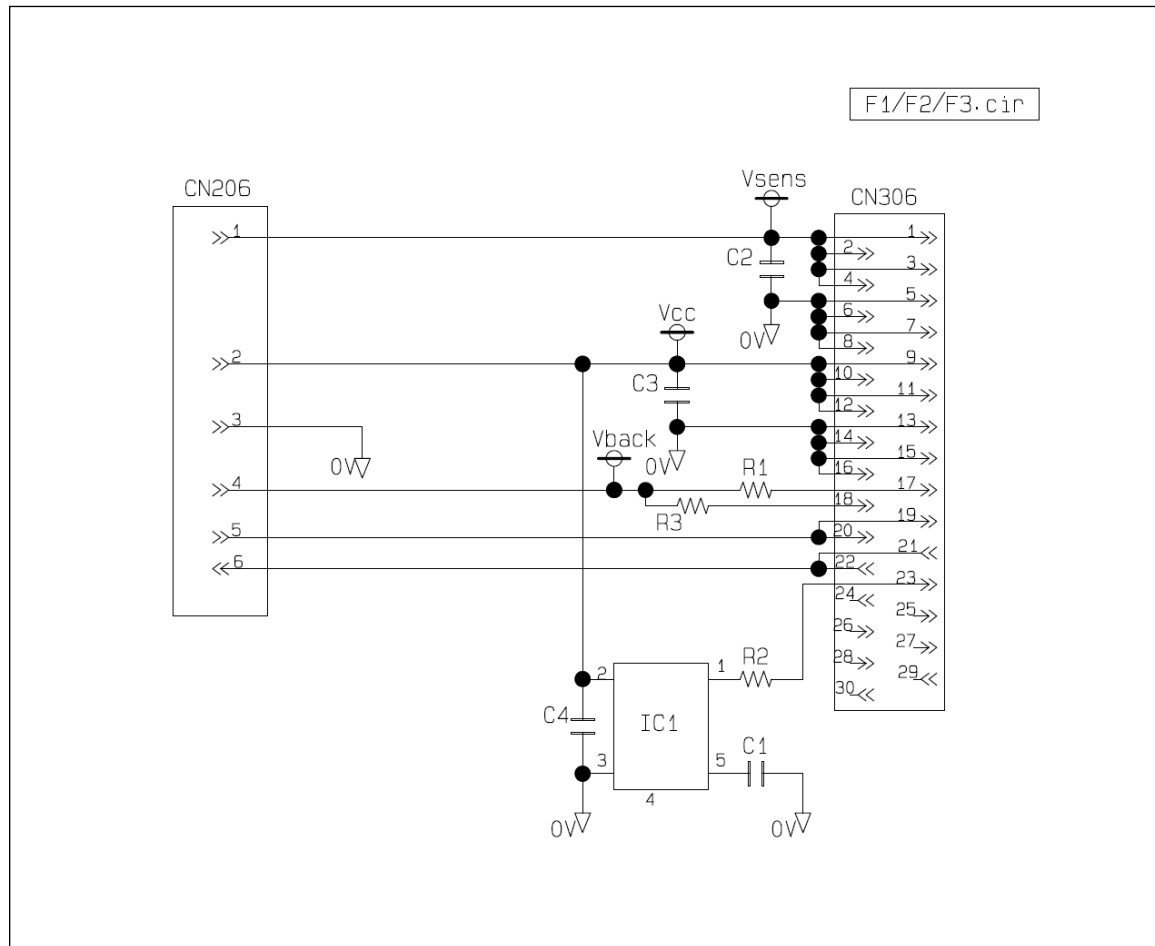


All drawings are view of parts side
SCALE 1:1

MARK	DIAGRAM	HOLE	MEMO
①	φ 0.3	TH	
○	φ 0.5	TH	
⊙	φ 0.9 x 2.1	TH	
⊗	φ 0.65	NTH	
⊕	φ 4.2	NTH	

SPECIFICATION FOR PCB

・PCB No.	: RKP-92711P
・Material	: Glass epoxy
・Thickness	: 1.6mm
・Layer number	: 2
・Thickness copper film	: 35um
・Copper thickness of the via's	: 35um above.
・Minimum conductor width	: 0.3mm
・CTI	: 100 above



SCHEMATIC

PARTS LIST

Mark of drawing	Kind of parts	Rating / Model of parts	Remarks
IC1	IC (Low Voltage Detector)	R3116N221A [Nisshinbo]	
R1,R2,R3	Chip metal film fixed resistor or Chip jumper	10 - 1M ohm / 1%, 0.1W or 50m ohm max, 1A (1005)	
C1,C2,C3,C4	Chip multilayer capacitor inside F1/F2/F3.cir	Total capacitance 2.32uFmax	

All components may be replaced with equivalent components or may not be mounted.

注 記 NOTES		改版担当者 REV. BY	改版日 REVISED	名 称 NAME F-SENSOR PCB
改版回数 REV.	0	総頁数 PAGES	1	EAGLE3
承認 APPROVED	検 討 CHECKED	製 図 DRAWN	作成日 DATE	図 番 DWG. NO.
山田和則	小野圭	木村司	2024.2.21	E 3 - 6 9 9 1 - 6 5 2 1 - 0 0 - 0 1 K